

General Description

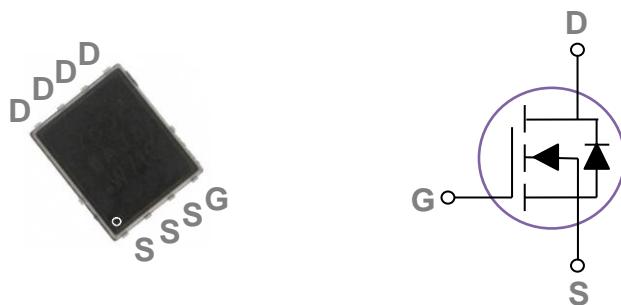
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDS(ON)	ID
40V	2.2mΩ	140A

Features

- 40V, 140A, RDS(ON) = 2.2mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

PPAK5X6 Pin Configuration



Applications

- Power Tools
- Load Switch
- LED applications
- Motor Drive Applications

Absolute Maximum Ratings T_c=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	40	V
V _{GС}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous (T _c =25°C) (Chip Limitation)	140	A
	Drain Current – Continuous (T _c =100°C) (Chip Limitation)	90	A
I _{DM}	Drain Current – Pulsed ¹	400	A
EAS	Single Pulse Avalanche Energy ²	200	mJ
IAS	Single Pulse Avalanche Current ²	20	A
P _D	Power Dissipation (T _c =25°C)	73.5	W
	Power Dissipation – Derate above 25°C	0.588	W/°C
T _{STG}	Storage Temperature Range	-50 to 150	°C
T _J	Operating Junction Temperature Range	-50 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	1.7	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	40	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=32\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$, $I_D=40\text{A}$	---	1.6	2.2	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1	---	3	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=40\text{A}$	---	60	---	S

Dynamic and switching Characteristics

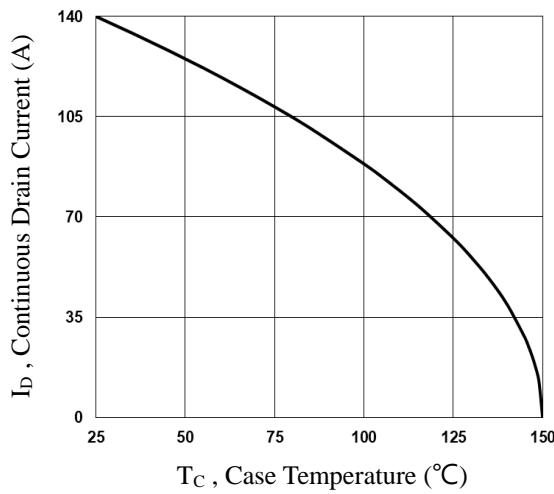
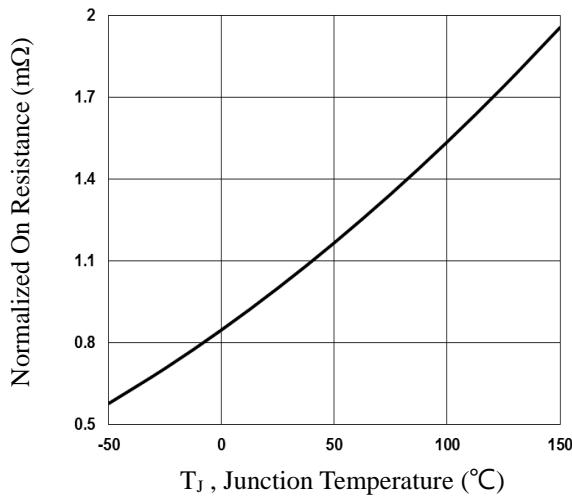
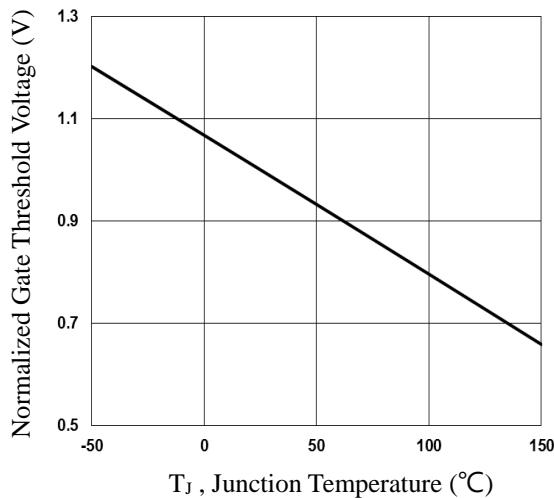
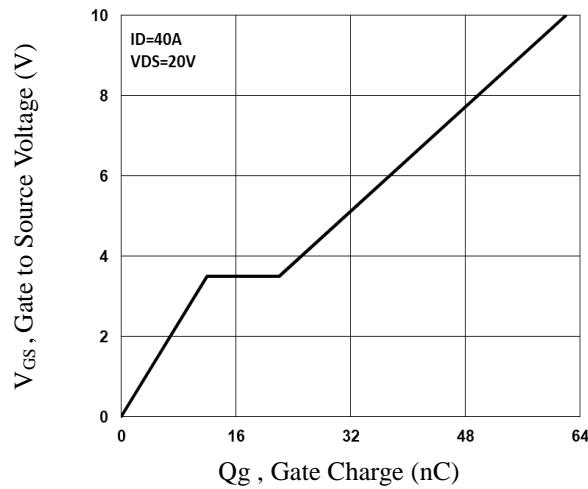
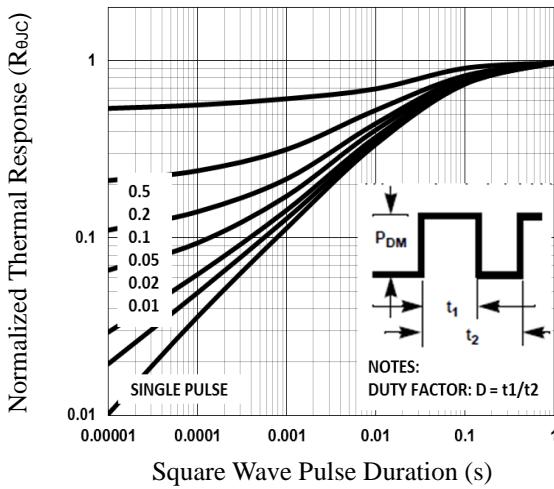
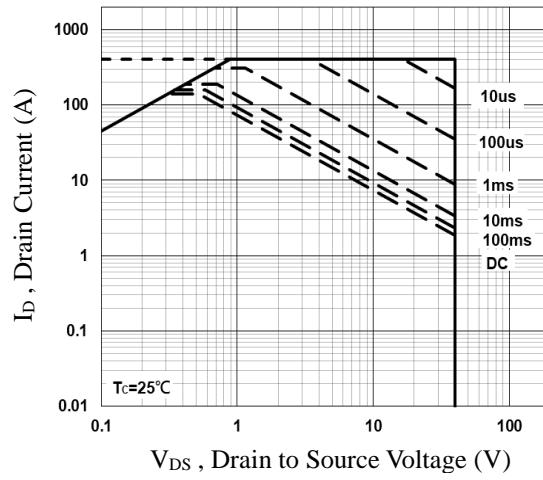
Q_g	Total Gate Charge ^{3,4}	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=40\text{A}$	---	62	120	nC
Q_{gs}	Gate-Source Charge ^{3,4}		---	12	24	
Q_{gd}	Gate-Drain Charge ^{3,4}		---	10	20	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{3,4}	$V_{\text{DD}}=20\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3\Omega$ $I_D=40\text{A}$	---	15	30	ns
T_r	Rise Time ^{3,4}		---	25	50	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{3,4}		---	68	140	
T_f	Fall Time ^{3,4}		---	26	52	
C_{iss}	Input Capacitance	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	4000	6000	pF
C_{oss}	Output Capacitance		---	150	235	
C_{rss}	Reverse Transfer Capacitance		---	2.5	10	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	2	4	Ω

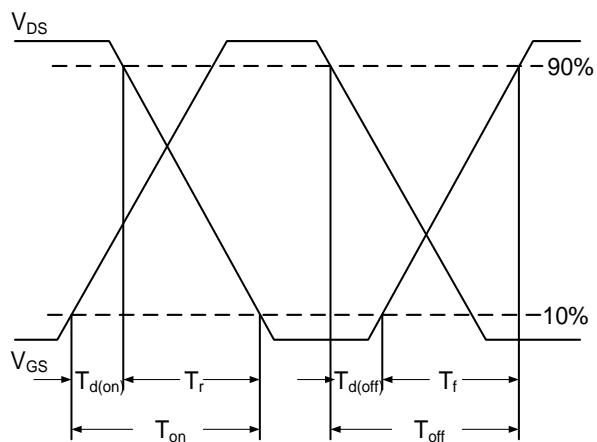
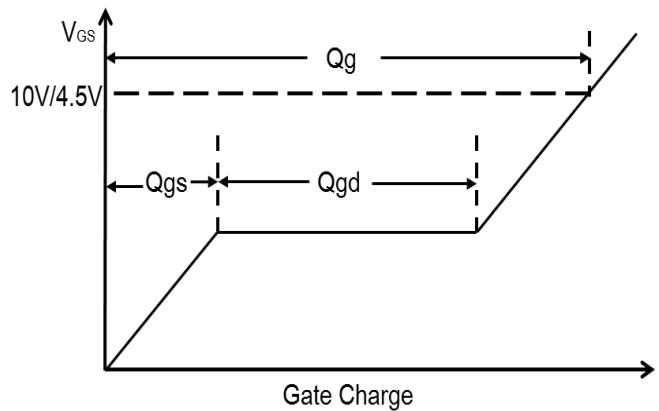
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	140	A
	Pulsed Source Current		---	---	280	A
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V
t_{rr}	Reverse Recovery Time	$V_{\text{GS}}=0\text{V}$, $I_s=40\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	---	48	---	ns
	Reverse Recovery Charge		---	55	---	nC

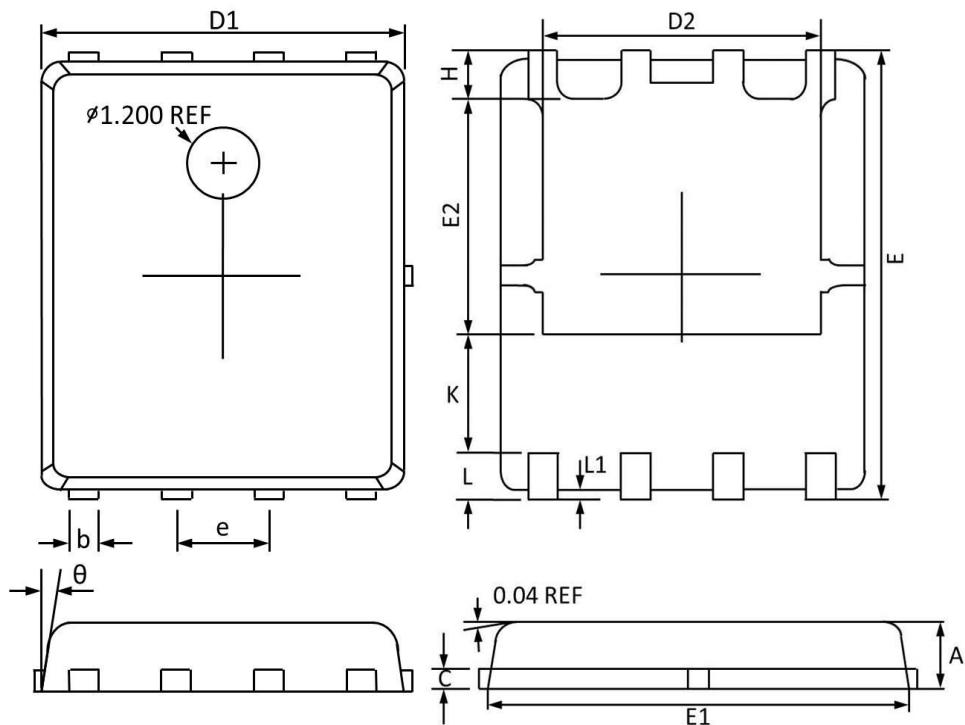
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=1\text{mH}$, $I_{\text{AS}}=20\text{A}$, Starting $T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. Tc

Fig.2 Normalized RDSON vs. Tj

Fig.3 Normalized Vth vs. Tj

Fig.4 Gate Charge Characteristics

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

Fig.8 Gate Charge Waveform

PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°